

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	1548	Chip adj scale adj package	USPAT; US-PGPUB
2	BRS	L4	48	L1 and (wiring adj layer) and stress and (slit or aperture or hole)	USPAT; US-PGPUB
3	BRS	L10	0	L7 and dummy	USPAT; US-PGPUB
4	BRS	L7	48	L4 and (pad or bump or terminal)	USPAT; US-PGPUB
5	BRS	L13	346	257/669.ccls.	USPAT; US-PGPUB
6	BRS	L16	7	L13 and (wiring adj layer) and stress and (slit or aperture or hole)	USPAT; US-PGPUB
7	BRS	L19	1	"4970574".PN.	USPAT
8	BRS	L20	1	"4916521".PN.	USPAT
9	BRS	L21	1	"4884123".PN.	USPAT
10	BRS	L22	651	(wiring adj layer) and (wiring adj pattern) and stress	USPAT; US-PGPUB
11	BRS	L25	582	L22 and (pad or electrode or terminal)	USPAT; US-PGPUB
12	BRS	L28	34	L25 and radial\$2	USPAT; US-PGPUB
13	BRS	L31	45	L25 and slit	USPAT; US-PGPUB

	Type	L #	Hits	Search Text	DBs
14	BRS	L3 4	124 2	257/787.ccls.	USPAT; US-PGPUB
15	BRS	L3 7	5	L34 and (wiring adj layer) and stress and (slit or aperture)	USPAT; US-PGPUB
16	BRS	L4 0	16	(wiring adj- layer) and (slit or aperture) and stress	EPO; JPO; IBM_TDB